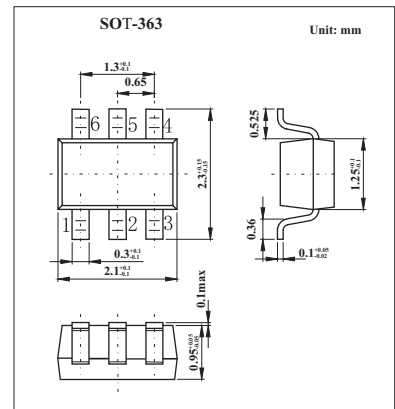
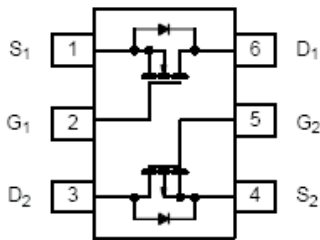


■ PIN Configuration



■ Absolute Maximum Ratings  $T_A = 25^\circ\text{C}$

Parameter	Symbol	N-Channel		P-Channel		Unit
		5 secs	Steady State	5 secs	Steady State	
Drain-Source Voltage	$V_{DS}$	20		-8		V
Gate-Source Voltage	$V_{GS}$	$\pm 12$		$\pm 8$		V
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ )* $T_A = 25^\circ\text{C}$	$I_D$	$\pm 0.70$	$\pm 0.66$	$\pm 0.60$	$\pm 0.57$	A
		$T_A = 85^\circ\text{C}$	$\pm 0.50$	$\pm 0.48$	$\pm 0.43$	$\pm 0.41$
Pulsed Drain Current	$I_{DM}$	$\pm 1$				A
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	0.25	0.23	-0.25	-0.23	A
Maximum Power Dissipation* $T_A = 25^\circ\text{C}$	$P_D$	0.3	0.27	0.3	0.27	W
		$T_A = 85^\circ\text{C}$	0.16	0.14	0.16	0.14
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150				$^\circ\text{C}$

\*Surface Mounted on 1" X 1" FR4 Board.

■ Thermal Resistance Ratings  $T_A = 25^\circ\text{C}$

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient*	$t \leq 5 \text{ sec}$	$R_{thJA}$	360	415	$^\circ\text{C/W}$
	Steady State		400	460	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	300	350	

\*Surface Mounted on 1" X 1" FR4 Board.



■ Electrical Characteristics TJ = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>Ds</sub> = V <sub>Gs</sub> , I <sub>D</sub> = 250 μA	N-Ch	0.6			V
		V <sub>Ds</sub> = V <sub>Gs</sub> , I <sub>D</sub> = -250 μA	P-Ch	-0.45			
Gate Body Leakage	I <sub>GSS</sub>	V <sub>Ds</sub> = 0 V V <sub>Gs</sub> = ±12V	N-Ch			±100	nA
		V <sub>Ds</sub> = 0 V V <sub>Gs</sub> = ±8V	P-Ch			±100	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>Ds</sub> = 16V, V <sub>Gs</sub> = 0 V	N-Ch			1	nA
		V <sub>Ds</sub> = -6.4V, V <sub>Gs</sub> = 0 V	P-Ch			-1	
		V <sub>Ds</sub> = 16 V, V <sub>Gs</sub> = 0 V, T <sub>J</sub> = 85°C	N-Ch			5	μA
		V <sub>Ds</sub> = -6.4V, V <sub>Gs</sub> = 0 V, T <sub>J</sub> = 85°C	P-Ch			-5	
On State Drain Currenta	I <sub>D(on)</sub>	V <sub>Ds</sub> ≥ 5 V, V <sub>Gs</sub> = 4.5 V	N-Ch	1.0			A
		V <sub>Ds</sub> ≤ -5 V, V <sub>Gs</sub> = -4.5 V	P-Ch	-1.0			
Drain Source On State Resistance*	r <sub>DS(on)</sub>	V <sub>Gs</sub> = 4.5 V, I <sub>D</sub> = 0.66A	N-Ch		0.320	0.385	Ω
		V <sub>Gs</sub> = -4.5 V, I <sub>D</sub> = -0.57A	P-Ch		0.510	0.600	
		V <sub>Gs</sub> = 2.5 V, I <sub>D</sub> = 0.40A	N-Ch		0.560	0.630	
		V <sub>Gs</sub> = -2.5 V, I <sub>D</sub> = -0.48A	P-Ch		0.720	0.850	
		V <sub>Gs</sub> = -1.8 V, I <sub>D</sub> = -0.20A	P-Ch		1.00	1.200	
Forward Transconductance*	g <sub>fs</sub>	V <sub>Ds</sub> = 10 V, I <sub>D</sub> = 0.66A	N-Ch		1.5		mS
		V <sub>Ds</sub> = -4 V, I <sub>D</sub> = -0.57A	P-Ch		1.2		
Diode Forward Voltage*	V <sub>SD</sub>	I <sub>s</sub> = 0.23A, V <sub>Gs</sub> = 0 V	N-Ch		0.8	1.2	V
		I <sub>s</sub> = -0.23A, V <sub>Gs</sub> = 0 V	P-Ch		-0.8	-1.2	
Total Gate Charge	Q <sub>g</sub>	N-Channel V <sub>Ds</sub> = 10 V, V <sub>Gs</sub> = 4.5V, I <sub>D</sub> = 0.66A	N-Ch		0.8	1.2	pC
Gate Source Charge	Q <sub>gs</sub>	P-Channel	N-Ch		0.06		
			P-Ch		0.17		
Gate Drain Charge	Q <sub>gd</sub>	V <sub>Ds</sub> = -4 V, V <sub>Gs</sub> = -4.5 V, I <sub>D</sub> = -0.57A	N-Ch		0.30		
			P-Ch		0.16		
Turn On Time	t <sub>d(on)</sub>	N- Channel V <sub>DD</sub> = 10 V, R <sub>L</sub> = 20 Ω	N-Ch		10	20	ns
Rise Time	t <sub>r</sub>	I <sub>D</sub> = 0.5 A, V <sub>GEN</sub> = 4.5V, R <sub>g</sub> = 6 Ω	N-Ch		16	30	
			P-Ch		25	50	
Turn Off Delay Time	t <sub>d(off)</sub>	P-Channel V <sub>DD</sub> = -4 V, R <sub>L</sub> = 8 Ω	N-Ch		10	20	
			P-Ch		10	20	
Fall Time	t <sub>f</sub>	I <sub>D</sub> = -0.5 A, V <sub>GEN</sub> = -4.5 V, R <sub>g</sub> = 6 Ω	N-Ch		10	20	
			P-Ch		10	20	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 0.23 A, di/dt = 100 A/ μs	N-Ch		20	40	
		I <sub>F</sub> = -0.23 A, di/dt = 100 A/ μs	P-Ch		20	40	

\* Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.